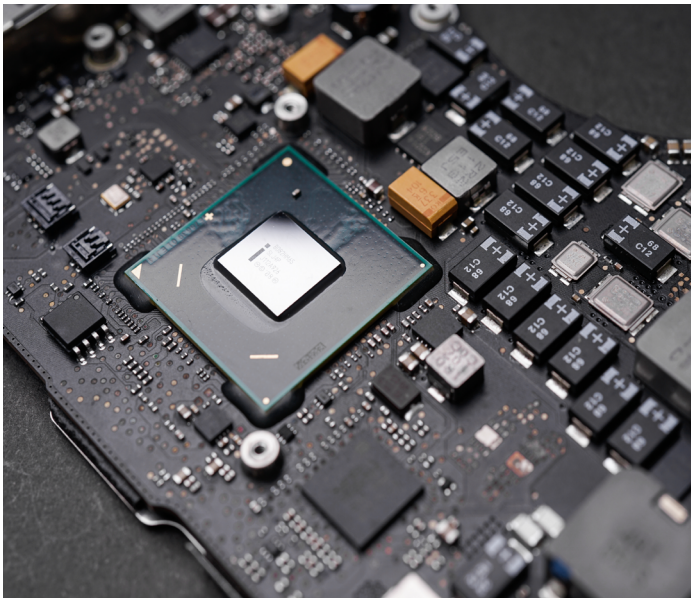
ALPHA® HiTech Edgebond

An Epoxy Material to be Dispensed on the Corners or Edges of the BGA

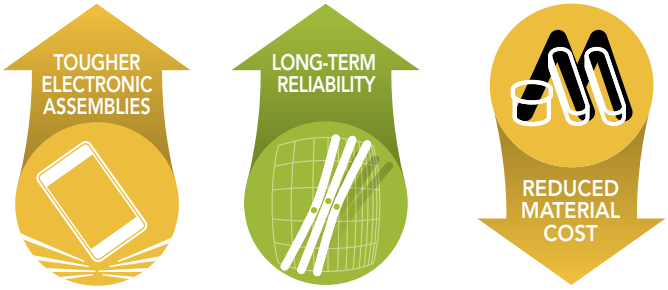
Dispense and Cure on 4 Corners of BGA

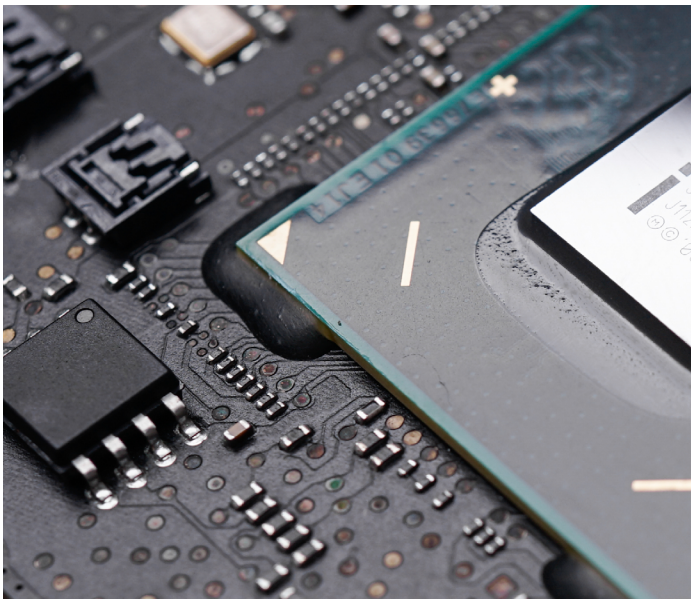
ALPHA HiTech Edgebond is a one component, heat curable material. The cured Edgebond will help to strengthen the soldered assembled component so it can pass reliability tests such as Drop Shock, Impact Bend and Thermal Cycle (TCT).



KEY FEATURES

- An excellent lower cost option to conventional underfilling process since higher material volume for capillary flow is not required
- Offers an effective process option to conventional underfilling process
- Has excellent adhesion to FR4
- Excellent TCT Reliability Performance
- Halogen Free





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ALPHA HiTech		CF12-4485B	CF31-4010
Typical Uncured Material Properties			
Chemical Type		Epoxy	Epoxy
Color		Black	White
Halogen Status		Halogen Free	Halogen Free
Viscosity Method		RVD-II Brookfield, 30 rpm@25°C	Malcom PC-10A, 30 rpm, 25°C
Viscosity , kcps		5.0 - 7.0	12.0 - 22.0
6 month Storage Temperature, °C		1 - 10°C	< - 20°C
Pot Life, days		7	3
Cure Condition, °C/min		110 /30; 120/20; 130/15; 150/10	120/30; 130/10; 150/7
Typical Cured Materials Properties			
Tg (°C)		105	170
CTE, TMA (ppm)	α1	56	25
	α2	191	70
Shore D Hardness (25°C)		80 -90	80 -90
Thermal Cycling Test, -40°C + 125°C, 30 min, SAC305		Pass 1,500 cycles	Pass 2,700 cycles
Thermal Cycling Test, -40°C + 150°C, 30 min, Innolot		NA	Pass 3,000 cycles
Reworkable		No	Yes

End Market

MacDermid Alpha ELECTRONICS SOLUTIONS

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Alpha is a product brand of MacDermid Alpha Electronics Solutions.

For more information, contact us at Assembly@MacDermidAlpha.com